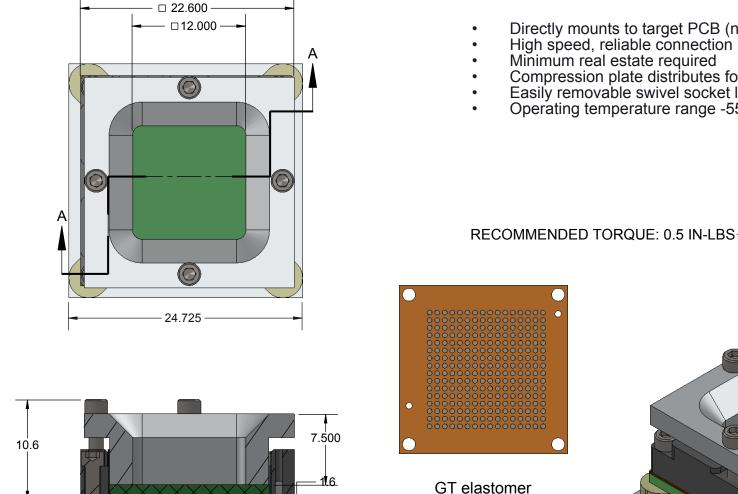
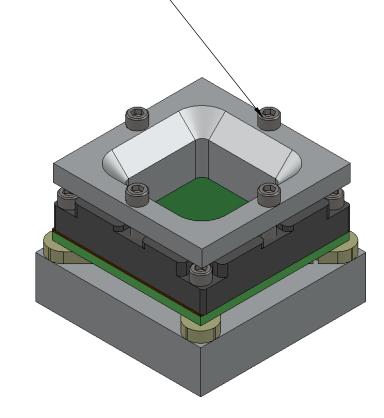
# GT BGA Socket - Direct mount, solderless



## Features

- Directly mounts to target PCB (needs tooling holes) with hardware

- High speed, reliable connection Minimum real estate required Compression plate distributes forces evenly Easily removable swivel socket lid Operating temperature range -55C to +160C



## Description: GT Open top Socket for 17x17mm 1mm pitch BGA256

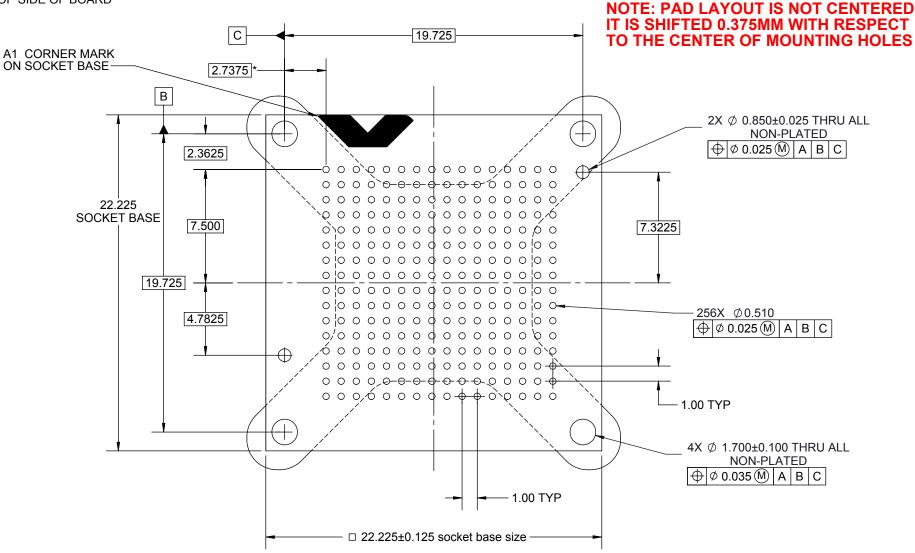
**SECTION A-A** 

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

7.9

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	GT-BGA-2026 Drawing Material: N/A		STATUS: Released	SHEET: 1 OF 4	REV. A
•	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 20.48	ENG: V. Panavala	DRAWN BY: M. Raske	SCALE: 5:2
			FILE: GT-BGA-2026 Dwg	DATE: 06/18/2015	



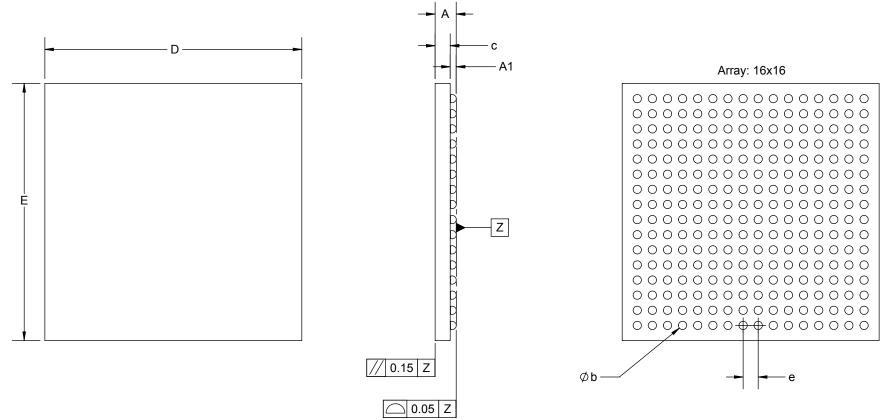
## Description: Recommended PCB Layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

#### Target PCB Recommendations Total Thickness: 1.6mm min. Plating: Gold Immersion, Silver Immersion or Solder PCB Pad Height: same or higher than solder mask

GT-BGA-2026 Drawing	s, Inc. Finish: N/A 204 Weight: 20.48	STATUS: Released	SHEET: 2 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204		ENG: V. Panavala	DRAWN BY: M. Raske	SCALE: 4:1
www.ironwoodelectronics.com		FILE: GT-BGA-2026 Dwg	DATE: 06/18/2015	

## **IRONWOOD COMPATIBLE PACKAGE CODE: BGA256E**



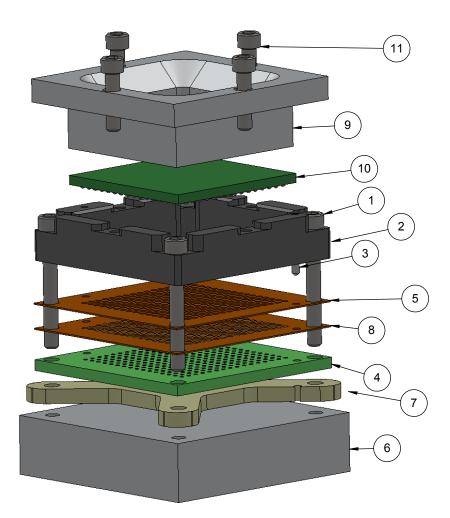
- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

#### **Description: Compatible Device**

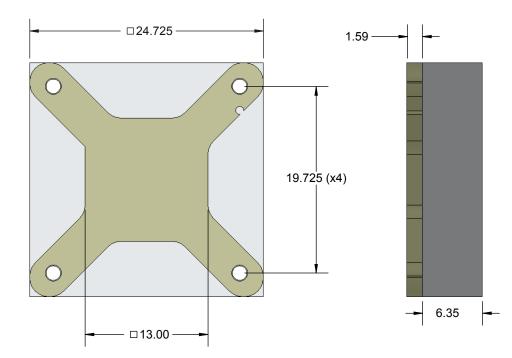
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

DIM	MIN	MAX
Α	1.0	2.0
A1	0.29	0.43
b	0.5	0.6
D	16.8	17.2
Е	16.8	17.2
е	1.0	

GT-BGA-2026 Drawing	Material: N/A Finish: N/A Weight: 20.48	STATUS: Released	SHEET: 3 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204		ENG: V. Panavala	DRAWN BY: M. Raske	SCALE: 4:1
www.ironwoodelectronics.com	troight 20.10	FILE: GT-BGA-2026 Dwg DATE: 06	DATE: 06/18/2015	



ITEM NO.	DESCRIPTION	Material
1	Mounting Screw	Stainless Steel
2	Socket Base	Aluminum Alloy
3	Dowel Pin	Stainless Steel
4	Target PCB	High Temp FR4
5	Ball Guide; BGA256, 16x16 arr 1mm pitch 0.375 offset	Kapton Polyimide/Cirlex
6	Backing Plate	Aluminum Alloy
7	Insulation Plate for 17x17mm IC	FR4 Standard
8	GT Elastomer 17x17mm IC 1mm pitch 16x16 array	Conductive Elastomer
9	Socket Lid/Compression Plate	7075-T6 Aluminum Alloy
10	TEST CHIP	High Temp FR4
11	#0-80 X .25 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel



## Description: Socket, Backing Plate Detail

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances</u>; Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

## INSULATION AND BACKING PLATE DETAIL

		STATUS: Released	SHEET: 4 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204	Weight: 20.48	ENG: V. Panavala	DRAWN BY: M. Raske	SCALE: 5:2
www.ironwoodelectronics.com		FILE: GT-BGA-2026 Dwg	DATE: 06/18/2015	